area of each aperture **16**. It will be noted that the first and third variants can be combined, with projecting portions **18** then being superposed on projecting zones **40**.

**[0060]** The various variants of the first embodiment of an assembly according to the invention, which have been described up until now, are characterized in that distinct zones on the edge of the electronic module, in particular on the substrate, are superposed on corresponding peripheral areas of the plate aperture, which houses said electronic module. The thickness of these peripheral areas is preferably smaller than that of the pierced plate. According to the invention, said edge zone and said peripheral area, which is superposed thereon, are assembled to each other so that the electronic module is secured in the plate aperture. The edge zone of the electronic module can directly abut against the corresponding peripheral area or be connected thereto via a resin film. Material connections are thus created between the electronic module and the pierced plate by means of specific zones on the edge of the electronic module, located opposite corresponding peripheral zones of the aperture, in which the electronic module is arranged.

**[0061]** FIG. **8** shows a fourth, particular variant of the first embodiment of an assembly of the invention. Assembly **44** is formed by a frame **14** that includes at least one aperture **16**, which is separated into two secondary apertures by a crossbeam **46** whose thickness is less than that of plate **14**. One could say that aperture **16** has two secondary apertures or equally that there are two apertures separated by a relatively narrow crossbeam. Electronic module **2** is arranged so that there are no electronic elements in a central area of substrate **12**, which is superposed on crossbeam **46** once module **2** has been inserted in aperture **16**. Module **2** is assembled to plate **14** via horizontal member **46**, to which module **2** is, for example, welded or bonded. Other assembling means could be provided by those skilled in the art.

**[0062]** In all of the variants of the first embodiment of an assembly according to the invention that have been described, the thickness of the areas of plate **14** that are peripheral to apertures **16** is preferably smaller than the thickness of the plate in general. It will be noted that other variants with a plate of constant thickness could be envisaged. In such case, substrate **12** is located above plate **14**, with the electronic elements in aperture **16**.

**[0063]** FIG. **9** shows a second embodiment of an assembly **50** according to the invention. The references that were described above will not be described again in detail here. This embodiment is characterized in that electronic module **2** is assembled to plate **14** via portions of adhesive strip **52**, in particular two portions. In this embodiment, electronic module **2** is entirely contained within the corresponding aperture **16** and has no parts superposed on plate **14**. The adhesive strip portions **52** define material connections between each electronic module and the pierced plate. These portions **52** can be arranged on either side of electronic module **2**. In the example of FIG. **9**, these portions **52** form a bridge between substrate **12** of module **2** and the peripheral area of aperture **16**. These portions are arranged on the opposite side to the electronic elements carried by substrate **12**. This example is in no way restrictive.

**[0064]** This second embodiment is characterized generally by the arrangement of strips formed of distinct material elements forming bridges between the edge of the electronic modules and the corresponding peripheral areas of the apertures housing the electronic modules. An "adhesive strip portion" means generally a strip portion with a surface that adheres both the plate **14** and to substrate **12**. The adherence must be sufficient to hold the electronic module in the corresponding aperture **16** during transport and handling of assembly **50**, and also during the steps of the card manufacturing method, in which this assembly **50** is produced as a constituent element in the batch of simultaneously manufactured cards.

**[0065]** FIG. **10** shows an advantageous variant of the second embodiment of an assembly **56**. The material connection or bridge between the electronic module and the peripheral area of aperture **16** in plate **14** is achieved here via self-adhesive discs **58**. The peripheral area of each aperture has notches **60** defining two small intermediate steps. The parts of self-adhesive discs **58** superposed on plate **14** are arranged inside these notches **60** in order to avoid creating any excessive thickness relative to frame **14**. The depth of notches **60** can be relatively small, at least equal to the thickness of disc **58**, or, conversely, their depth can be relatively large but less than the thickness of frame **14**. The references that have already been described are not all described again here.

**[0066]** FIG. **11** shows a third embodiment of an assembly according to the invention. This assembly **62** also includes a pierced plate **14** and electronic modules **2** arranged in apertures **16**. These modules **2** are assembled to plate **14** here by heat-reactivatable adhesive wires **64**. These heat-reactivatable adhesive wires **64** pass through plate **14** and, in particular, apertures **16**. Each heat-reactivatable adhesive wire **64** is arranged to adhere to plate **14** and to the modules **2** through which it passes. In the example shown in FIG. **11**, each electronic module **2** is held in the corresponding aperture **16** by two wires **64** arranged in proximity to two opposite edges of the module. The heat-reactivatable adhesive wire **64** can be a wire made of synthetic or natural material, or covered with adhesive. In another variant, the wire itself is formed by a solid resin, which can be made to adhere by applying heat or ultra-violet light. Of course, in another variant, an adhesive strip that passes through apertures **16** can form wire **64**. In another variant, the heat-reactivatable adhesive wires could pass grooves made in plate **14** between two adjacent apertures **16**, to prevent the wires causing excessive thickness relative to plate **14**.

**[0067]** Heat-reactivatable adhesive wires **64** can be added before or after the electronic modules, depending upon the arrangement anticipated. Likewise, the heat-reactivatable adhesive wires can be provided on the side of substrate **12** opposite the electronic elements carried by the substrate, as shown in FIG. **11**, or located elsewhere, relative to substrate **12**, on the same side as the electronic elements. The heat-reactivatable adhesive wire can adhere either to substrate **12** or to some of the electronic elements above which it is arranged. Those skilled in the art will understand that the possible variants are numerous. The assembly method here comprises an element that adheres to the electronic module and to plate **14** and passes through spaces **16** from a peripheral area to another peripheral area of each aperture **16**. FIG. **11** shows the heat-reactivatable adhesive wires parallel to one edge of rectangular apertures **16**, but the wires could very well be arranged obliquely, particularly along a diagonal direction of said apertures **16**.

**[0068]** FIGS. **12** to **15** show two variants of a fourth embodiment of an assembly according to the invention. The references that have already been described previously will not be described again here in detail. This fourth embodiment